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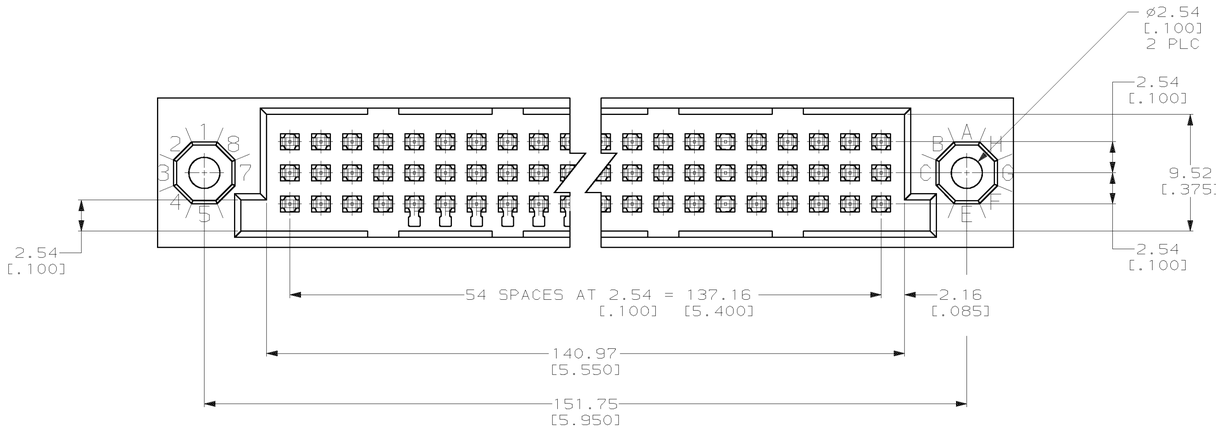
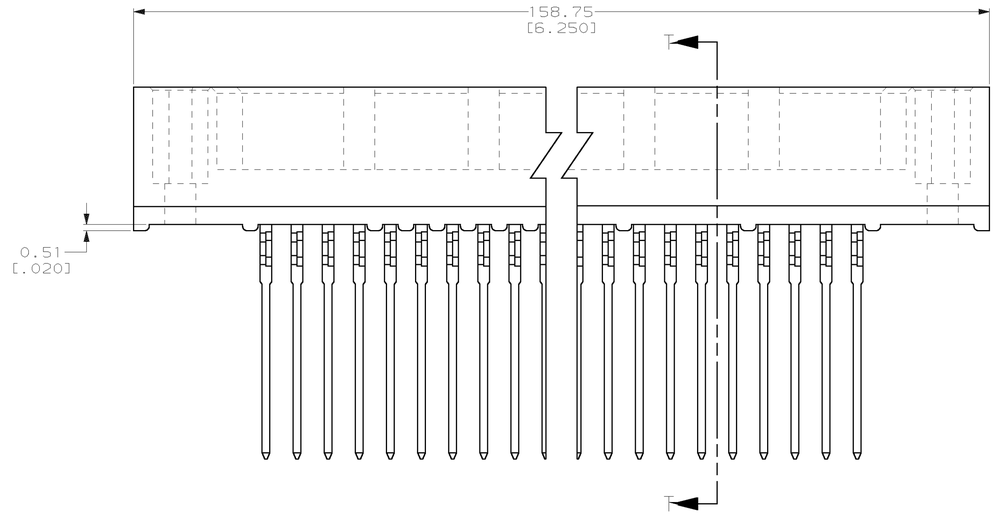
LOC	DIST
AD	25

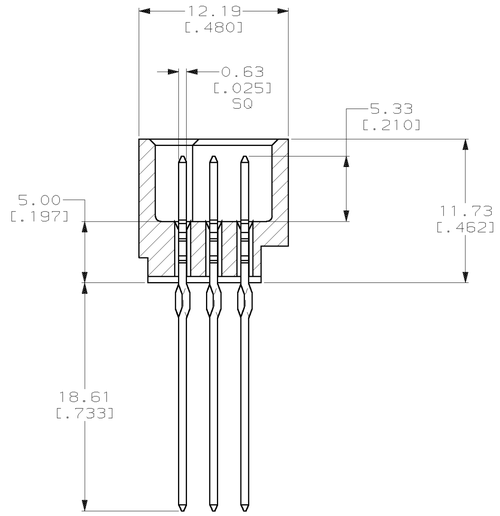
REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	A3	ECN AD-2589 M.S.	8-88	–	–
	B	REV PER EC 0U1B-0131-01	15 OCT 01	BC	WM

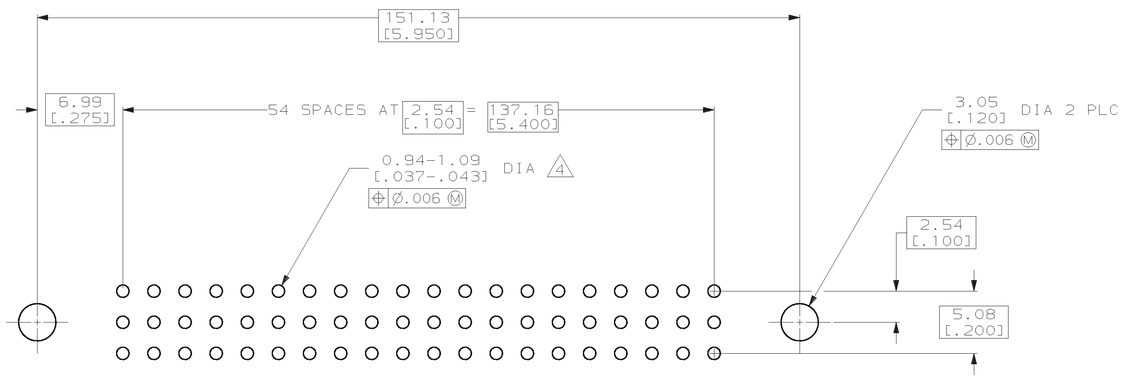


1. HOUSING MATERIAL: THERMOPLASTIC, BLACK.
2. CONTACT MATERIAL: PHOS. BRONZE.
3. CONTACT FINISH: 0.76µm[.000030] MIN GOLD IN CONTACT AREA OVER 1.27µm-2.54µm[.000050-.000100] NICKEL, TIN-LEAD PLATED POSTS.
4. ACTION PIN POSTS REQUIRE 2.36[.093] MIN THICK P.C. BOARD. RECOMMENDED P.C. BOARD HOLES ARE 1.151 [.0453] DIA PLATED THRU WITH 0.025-0.076 [.001-.003] COPPER, WITH 0.0076 [.0003] MIN TIN-LEAD PLATING, FINISHED HOLE AFTER PLATING 0.94-1.09 [.037-.043] DIA.





SECTION T-T



RECOMMENDED P.C. BOARD LAYOUT

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